

| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | : Not In VersionControl |
|----------------------------------|--------------------|-------------|----------|-------------------------|
| LAYER NAME = Top Overlay | | | | |
| PLOT NAME = Top Overlay | GENERATED : 1/19/2 | 015 2:15:31 | PM | TEXAS INSTRUMENTS |



| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | : Not In VersionControl |
|----------------------------------|--------------------|-------------|----------|-------------------------|
| LAYER NAME = Top Solder | | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 1/19/2 | 015 2:15:32 | PM | TEXAS INSTRUMENTS |

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| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | : Not In VersionControl |
|----------------------------------|--------------------|---------|----------|-------------------------|
| LAYER NAME = Top Layer | | | | |
| PLOT NAME = Top Layer | GENERATED : 1/19/2 | 2:15:33 | PM | TEXAS INSTRUMENTS |



| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV | : Not In VersionControl |
|----------------------------------|--------------------|---------|---------|-------------------------|
| LAYER NAME = | | | | |
| PLOT NAME = MidLayer1 | GENERATED : 1/19/2 | 2:15:33 | PM | TEXAS INSTRUMENTS |



| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV | : Not In VersionControl |
|----------------------------------|--------------------|---------|---------|-------------------------|
| LAYER NAME = | | | | |
| PLOT NAME = MidLayer2 | GENERATED : 1/19/2 | 2:15:34 | PM | TEXAS INSTRUMENTS |



| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | Not In VersionControl |
|----------------------------------|--------------------|---------|----------|-----------------------|
| LAYER NAME = Bottom Layer | | | | |
| PLOT NAME = Bottom Layer | GENERATED : 1/19/2 | 2:15:35 | PM | TEXAS INSTRUMENTS |



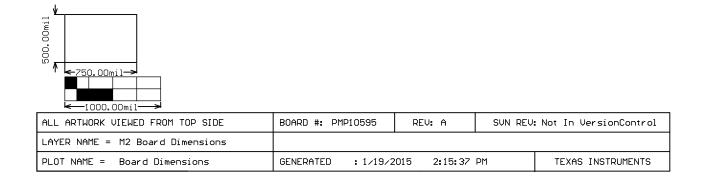
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV | : Not In VersionControl |
|----------------------------------|--------------------|-------------|---------|-------------------------|
| LAYER NAME = Bottom Solder | | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 1/19/2 | 015 2:15:35 | PM | TEXAS INSTRUMENTS |



| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | : Not In VersionControl |
|----------------------------------|--------------------|-------------|----------|-------------------------|
| LAYER NAME = Bottom Overlay | | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 1/19/2 | 015 2:15:36 | PM | TEXAS INSTRUMENTS |

| | | | Symbol | Quantity | Finished Hole Size | Plated | Hole Type |
|--|---|--|--------------------|----------|--------------------|--------|-----------|
| ~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~ | | | \bigtriangledown | 11 | 10.00mil (0.254mm) | РТН | Round |
| °°°° | v | | | 3 | 39.37mil (1.000mm) | РТН | Round |
| | | | | 14 Total | | | |

| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10595 | REV: A | SVN REV: | : Not In VersionControl |
|----------------------------------|--------------------|---------|----------|-------------------------|
| LAYER NAME = Drill Drawing | | | | |
| PLOT NAME = Drill Drawing | GENERATED : 1/19/2 | 2:15:36 | PM | TEXAS INSTRUMENTS |



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